

**IMPROVED SURFACE MOUNT PACKAGE****ABSTRACT OF THE DISCLOSURE**

Space-efficient packaging of microelectronic devices permits greater functionality per unit PC board surface area. In certain embodiments, packages having leads 5 of a reverse gull wing shape reduce peripheral footprint area occupied by the leads, thereby permitting maximum space in the package footprint to be allocated to the package body and to the enclosed die. Embodiments of packages in accordance with the present invention may also reduce the package vertical profile by featuring recesses for receiving lead feet ends, thereby reducing clearance between the package bottom and the PC board. Providing a linear 10 lead foot underlying the package and slightly inclined relative to the PC board further reduces vertical package profile by eliminating additional clearance associated with radiiuses of curvature of J-shaped leads.

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